RECIPIENT

SPECIFICATIONS

Product No. : X1G000221005800

MODEL: **TCO-7086X1A4**

SPEC. No. : A08-989-0B

DATE: Mar. 23. 2009

EPSON TOYOCOM CORPORATION

8548 Naka-minowa Minowa-machi Kamiina-gun Nagano-ken 399-4696 Japan



SPECIFICATIONS

1. Application

This document is applicable to the crystal oscillator that is delivered to Nokia Siemens Networks Transport System Ltd from Epson Toyocom Corp.

This product is compliant with RoHS Directive.

This Product supplied (and any technical information furnished, if any) by Epson Toyocom Corporation shall not be used for the development and manufacture of weapon of mass destruction or for other military purposes.

Making available such products and technology to any third party who may use such products or technologies for the said purposes are also prohibited.

This product listed here is designed as components or parts for electronics equipment in general consumer use.

We do not expect that any of these products would be incorporated or otherwise used as a component or part for the equipment, which requires an extra high reliability, such as satellite, rocket and other space systems, and medical equipment, the functional purpose of which is to keep life.

2. Product No. / Model

The product No. of this crystal oscillator is X1G000221005800. The model is TCO-7086X1A4.

3. Packing

It is subject to the packing standard of Epson Toyocom Corp.

4. Warranty

Defective parts which are originated by us are replaced free of charge in case defects are found within 12 months after delivery.

5. Amendment and abolishment

Amendment and/or abolishment of this specification are subject to the agreement between both parties.

6. Contents

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Parameter	Symbol	Value	Unit	Note
Supply voltage	Vcc	-0.5 to +7.0	V	
Input voltage	VIN	-0.5 to Vcc+0.5	V	
Storage temperature range *	Tstg	-55 to +125	°C	Stored as bare product after unpacking.

[1] Absolute maximum ratings

[2] Operating range

		Value				
Parameter	Symbol	Min.	Тур.	Max.	Unit	Note
Supply voltage	Vcc	2.97	3.30	3.63	V	
Supply voltage	GND	0.0	-	0.0	V	
Input voltage	VIN	GND	-	Vcc	V	
Output frequency	fo	-	2.048	-	MHz	
Operating temperature range	T_use	-40	-	+85	°C	
Output load condition	L_CMOS	-	-	15	pF	

*1 Start up time(0 %Vcc 90 %Vcc) of power source should be more than 150 μ s.

*2.By-pass capacitor (approx. 0.01 μ F to 0.1 μ F) should be placed closely between Vcc and GND.

[3] Frequency characteristics

1) Output frequency (fo) 2.048MHz

Parameter	Symbol	Value	Unit	Note
Frequency tolerance *	f_tol	$\pm 50 imes 10^{-6}$	-	$T_use = -40 \text{ °C} \sim +85 \text{ °C}$
Aging	f_aging	$\pm 5 imes 10^{-6}$	-	+25 °C, Vcc=3.3 V, 1year

* This includes initial frequency tolerance, temperature characteristics and input voltage characteristics.

[4] Terminal assignment



Name	No.	Туре	Terminal description					
ST	#1	INPUT	Stand by control terminal					
			Function	Osc.circuit	Output status			
			High or OPEN Enable		Specified frequency is output			
			Low	Disable	Output becomes Hi-Z			
GND	#2	-	GND terminal	GND terminal				
OUT	#3	OUTPUT	Clock output terminal					
Vcc	#4	-	Vcc terminal	Vcc terminal				

[5] Electrical characteristics

				(-		
Parameter	Symbol	Value		Unit	Note	
		Min.	Туре	Max.		
Oscillation start up time	t_str	-	-	10	ms	90 % Vcc to be 0 s
Current consumption	Icc	-	-	20	mA	No load
Rise time *1	Tr	-	-	6	ns	$10 \% V_{CC} \rightarrow 90 \% V_{CC}$
Fall time *1	Tr	-	-	6	ns	$90 \% V_{CC} \rightarrow 10 \% V_{CC}$
Symmetry *1	SYM	40	-	60	%	50 %Vcc Level
High level output voltage	V _{OH}	90%Vcc	-	-	V	-
Low level output voltage	V _{OL}	-	-	0.4	V	-
High level input voltage	V _{IH}	70 %Vcc	-	-	V	ST terminal
Low level input voltage	V_{IL}	-	-	30 %Vcc	V	ST terminal
Disable time *2	tstp	-	-	150	ns	$\overline{\text{ST}}$ terminal HIGH \rightarrow LOW
Enable time *2	tsta	-	-	10	ms	$\overline{\text{ST}}$ terminal LOW \rightarrow HIGH

(Please see page 2 [2] Operating range)

Please see [6] Test circuit.

*1 Please see [7] 1) Output waveform. *2 Please see [7] 2) ST function and timing.

[6] Test circuit

1) Waveform observation





2) Current consumption



3) Condition

- (1) Oscilloscope
 - Bandwidth should be 5 times higher than DUT's output frequency.
 - Probe ground should be placed closely from test point and lead length should be as short as possible.
- (2) CL includes probe capacitance.
- (3) By-pass capacitor (0.01 μ F to 0.1 μ F) is placed closely between Vcc and GND.
- (4) Use the current meter whose internal impedance value is small.

(5) Power supply

• Impedance of power supply should be as low as possible.

[7] Timing chart

1) C-MOS load



2) $\overline{\text{ST}}$ function and timing

ST input level	Oscillation circuit	Output				
"H" or OPEN	Oscillation	Enable : Specified frequency is output				
"L"	Oscillation stop	Disable : high impedance				



*1 The time taken from $\overline{ST}=V_{IL}$ to OUT=Disable (high impedance).

*2 The time taken from $\overline{\text{ST}}=V_{\text{IH}}$ to OUT=Enable.

Output start : VOH \geq 90 %VCC, VOL \leq 10 %VCC, fout = fo \pm 1 000×10⁻⁶

[8] Environmental and mechanical characteristics

		Value *1		Test Conditions			
No.	Item	$\Delta f / f * 2$	Electrical				
		$[1 \times 10^{-6}]$	Characteristics				
1	High tomporature storage	*2 + 10		+85 °C ± 3 °C × 1 000 h			
1	nightemperature storage	·3 ±10		*JIS-C-0021			
				$-55 ^{\circ}\text{C} \leftrightarrow +125 ^{\circ}\text{C}$			
2	Temperature cycle	$*3 \pm 10$		30 min. at each temperature 10 cycles			
				*MIL-STD-883D 1010.7(B)			
3	Temperature humidity	*3 ±10		+85 °C ± 2 °C × 85 %RH ± 5 %RH × 250 h			
4	Low temperature storage	*3 ±10		-40 °C ± 3 °C × 1 000 h			
			Satisfy	10 Hz to 85 Hz amplitude 1.5 mm			
~	Vibration	. 10	Item [5]	85 Hz to 2 000 Hz acceleration 20G			
5		± 10	after test.	$10 \text{ Hz} \rightarrow 2000 \text{ Hz} \rightarrow 10 \text{ Hz} = 20 \text{ min./cycle}$			
				$12 h (4 h \times 3 \text{ directions})$			
				*MIL-STD-202E Method 205E(D)			
-				5000 G			
6	Shock	± 10		1/2 sine wave 3 shocks in X,Y,Z			
			-	(Total of 9 shocks).			
				Dip termination into solder bath at			
7	Resistance to soldering heat	±10		$+260 \circ C \pm 10 \circ C$ for 5 to 10 s.			
				*MIL-STD-202E Method 210A(A)			

(The company evaluation condition we evaluate it by the following examination item and examination condition.)

< Notes >

*1 Each test done independently.

*2 Measuring 1 h to 24 h later leaving in room temperature after each test.

*3 Initial values shall be measured after 24 h storage at room temperature after Pre-treatment. Pre-treatment: Reflow (3 times)

♦ Convection reflow conditions (Ref. IPC/JEDEC J-STD-020D)



[9] ESD sensitivity

• Electrostatic discharge (ESD)

Item	Value	Test procedure
Human Body Model	1500 V Min.	Ref. EIAJ ED-4701-1 C111A, 100 pF, 1.5 kΩ, 3 Pulses
(HBM)		
Machine Model	100 V Min.	Ref. EIAJ ED-4701-1 C111, 200 pF, 0 Ω, 1 Pulse
(MM)		

[10] Dimensions and marking layout

1) Dimensions



- The above marking layout shows only marking contents and their approximate position and it is not for font, size and exact position.
- We show output frequency to the third decimal place and round down the forth decimal place.

[11] Recommendable patterning

The soldering pad sample indicated as like following: Soldering position (Unit : mm)



[12] Notes

1) This device is made with C-MOS IC.

Please take necessary precautions to prevent damage due to electrical static discharge.

- Epson Toyocom recommends a 0.01 µF to 0.1 µF capacitor must be connected near Vcc between Vcc and GND to obtain stable operation and protect against power line ripple. (see [11])
- 3) Vcc and GND pattern shall be as large as possible so that high frequency impedance shall be small.
- 4) Epson Toyocom cannot recommend to put filtering element into power line so as to reduce noise. Oscillator might be unstable oscillation because high frequency impedance of power line become higher. When use filtering element, please verify electrical construction and or element's spec.
- 5) Epson Toyocom doesn't recommend to power on from intermediate electric voltage or extreme fast power on. Those powering conditions may cause no oscillation or abnormal oscillation.
- 6) Power ripple: 200 mV P-P max. Start up time (0 %Vcc→90 %Vcc) of power source should be more than 150 μs.
- 7) A long output line may cause irregular output, so try to make the output line as short as possible.
- 8) Other high-level signal lines may cause incorrect operation, so please do not place high level signal line close to this device.
- 9) This device contains a crystal resonator, so please don't expose excessive shock or vibration. Epson Toyocom recommends store device under normal temperature and humidity to keep the specification.
- 10) An automatic insertion is available, however, the internal crystal resonator might be damaged in case that too much shock or vibration is applied by machine condition.Be sure to check your machine condition in advance.
- 11) Ultrasonic cleaning can be used on this product, however, since the oscillator might be damaged under some conditions, please exercise caution in advance.
- 12) Epson Toyocom recommends to use and store under room temperature and normal humidity to secure frequency accuracy and prevent moisture.
- 13) Metal cap of this product is connected to GND. Please don't apply electrical voltage.
- 14) Side leads are connected to IC internally. Therefore be careful for short or a fall of insulation resistance etc.

15) Recommendation reflow times are less than 2 times.

When there was a soldering error, please do alteration with a soldering iron.

In this case, the iron ahead is equal to or less than +350 °C and asks within 5 s.

In case that this device is reflow soldered on the back side of your circuit board, please carefully verify the device is properly secured to prevent coming detached from card.

Soldering method	OK or NG
Reflow soldering (top side)	OK
Reflow soldering (back side)	OK
Solder pot (static solder pot / flow solder pot)	NG
Iron soldering	OK

[About soldering method]

TAPING SPECIFICATION

I. Application

This standard will apply to 7×5 Ceramic package. Spec : CA package

${\rm I\hspace{-1.5pt}I}$. Contents

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[2] Inner carton

a) Packing to antistatic bag



[4] Marking

- (1) Reel marking
 - Reel marking shall consist of :
 - 1) Parts name
 - 2) Quantity
 - 3) Manufacturing date or symbol
 - 4) Manufacturer's date or symbol
 - 5) Others (if necessary)
- (2) Inner carton marking
 - Same as reel marking.
- (3) Shipping carton marking
 - Shipping carton marking shall consist of :
 - 1) Parts name
 - 2) Quantity

[5] Quantity

• 1 000 pcs./reel

[6] Storage environment

- (1) To storage the reel at 15 °C to 35 °C, 25 %RH to 85 %RH of humidity.
- (2) To open the packing just before using.
- (3) Not to expose the sun.
- (4) Not to storage with some erosive chemicals.
- (5) Nothing is allowed to put on the reel or carton to prevent mechanical damage.

[7] Handling

• To handle with care to prevent the damage of tape, reel and products.

- PROCESS QUALITY CONTROL -

No. 708x - 00 - ASE - 1

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08. 2. 14 EPSON TOYOCOM CORP AT Business Unit

<u>No. 708x - 00 - ASE - 1</u>	AT	Business Unit	P. Kicoy Ham 1	lagan J. ahija				
Manufacturing pr	occes chart	No,	Section In Charge	Standards	Inspection, Control Item	Instruments	Inspection Methods	Record
		1	Inspection Section	Purchasing Specification Incoming Inspection Standard	Appearance Dimension	Microscope	Sampling	Data sheet
	inspection	2	China Plant (Production Section)	Manufacturing Instruction Sheet	Арреагансе	Microscope	Sampling	Data sheet
) Package Setting	3	China Plant (Production Section)	Manufacturing Instruction Sheet	Appearance	Містовсоре	Sampling	Data abcet
) Dio Attach	4	China Plant (Production Section)	Manufacturing Instruction Sheet	Bonding strength Appearance	Gauge Microscope	Sampling	Data sheet
	Wire Bonding	5	China Plant (Production Section)	Manufacturing Instruction Sheet	Appearance	Microscope	100% Inspection	Data sheet
	Appearance Inspection	6	China Plant (Production Section)	Manufacturing Instruction Sheet	Appearance	Microscope	Sampling 100% Inspection	Data sheet
	Crystal-Mounting	7	China Plant (Production Section)	Manufacturing Instruction Sheet	Аррежинсе	Microscope	Sampling	-
	Anneating	8	Chins Plant (Production Section)	Manufacturing Instruction Sheet	Frequency	Counter	Sampling.	Data sheet
B Frequency Adjus (Cry	Frequency Adjusting (Crystal)	9	China Plant (Production Section)	Manufacturing Instruction Sheet	Appearance Frequency	Microscope Counter	Sampling Sampling	Data sheet
9	Seam Welding	10	China Plant (Production Section)	Manufacturing Instruction Sheet	Leakage Inspection	Measuring equipment	100% Inspection	Data sheet
	Gross-Leakage	11	China Plant (Production Section)	Manufacturing Instruction Sheet	Leakage Inspection	Measuring equipment	100% Inspection	Data abset
	Fine-Loakage	12	China Plant (Production Section)	Manufacturing Instruction Sheet	Temperature	Thermometer	Onc / Day	Check sheet
	High Temp Treatment	13	China Plant (Production Section)	Manufacturing Instruction Sheet	Charaoteristic Inspection	Measuring equipment	100% Inspection	Data sheet
	LDL Inspection	14	Chins Plant (Production Section)	Manufacturing Instruction Sheet	Арреаталос	Visual inspection	Sampling	Data sheet
	Electrical Characteristic	15	China Plant (Production Section)	Manufacturing Instruction Sheet	Electrical Characteristic	Measuring equipment	100% Inspection.	Data sheet
	Temp Characteristic	16	China Flant (Production Section)	Manufacturing Instruction Sheet	Temp Characteristic	Measuring equipment	Sampling	Data sheet
	Appearance Inspection	17	China Plant (Production Section)	Manufacturing Instruction Sheet	Appearance	Microscope	Sampling	Data sheet
	Outgoing Inspection	18	China Plant (Inspection Section)	Delivery Specifications Outgoing Inspection Standard	Electrical Characteristic Appearance	Measuring equipment Microscope	Sampling	Data sheet
(1)	Taping	19	China Plant (Production Section)	Manufacturing Instruction Sheet	Tape peeling Strength	Peoling strength test machine	Sampling	Data shoot
(2)	Packing	20	China Plant (Production Control Section)	Manufacturing Instruction Shoot Daily Shipping List	Customens Type Quantity	_	-	Delivery Slip